



Press Release

August 19, 2026

Breaking through thermal barriers in AI and next-generation communications

Henkel launches LOCTITE ABLESTIK CDF900 series conductive die attach film

Taipei, Taiwan – Henkel Adhesive Technologies today announced the launch of Loctite ABLESTIK CDF900, its next-generation conductive die attach film (cDAF) series, at SEMICON Taiwan 2026. Delivering thermal conductivity exceeding 8 W/m-K, the new material is designed to help semiconductor manufacturers overcome rising thermal and stress challenges in AI, 5G and emerging 6G telecommunications, and high-performance computing (HPC) applications.

As AI, HPC, and next-generation communications drive higher chip frequencies, greater thermal design power, and more complex package architectures, efficient heat dissipation and stress control have become critical to device performance and reliability. Loctite ABLESTIK CDF900 addresses these challenges by combining high thermal conductivity with the precision and process consistency of a film-based die attach format.

Technical breakthrough for high-performance AI packaging

"Henkel is a global leader in conductive die attach film, with technology widely adopted in Wi-Fi communications, automotive electronics, and power devices. Today, Loctite ABLESTIK CDF900 pushes thermal performance to new heights while expanding applications into large-die packaging scenarios such as processors and AI chips. This offers customers broader design flexibility and superior thermal management solutions," said Kaihua Zhou, Head of Market Strategy for Semiconductor at Henkel Adhesive Technologies Electronics.

The core breakthrough of Loctite ABLESTIK CDF900 lies in its proprietary thermal filler technology, which substantially increases thermal conductivity to more than 8 W/m-K. This enables high-power components in mobile phones, processors, and Wi-Fi equipment to dissipate heat efficiently and maintain stable performance in demanding operating environments.

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Compared with competing liquid die attach adhesives, Loctite ABLESTIK CDF900's film-based format helps eliminate the risks of material bleed-out and non-uniform bondline thickness. This enables chip designers to achieve smaller, more precise die footprints within constrained spaces while enhancing overall package reliability and robustness.

Complete material solutions to address stress challenges in AI advanced packaging

To address warpage during processing and component stress issues inherent in large-die advanced packaging, Henkel continues to expand its material portfolio. The company has developed high-thermal-conductivity liquid molding compounds, high-performance capillary underfills, and diverse packaging material platforms to meet requirements for efficient heat dissipation, high reliability, and process flexibility. By reinforcing structural strength, toughness, and adhesion, Henkel's materials help mitigate stress imbalances while meeting the stringent reliability and high-volume manufacturing stability requirements of high-end AI packaging.

At SEMICON Taiwan 2026, Henkel will present its complete portfolio for critical advanced packaging applications, including underfill, conductive die attach film, liquid molded underfill, and non-conductive liquid adhesive technologies.

Kevin Becker, Senior Vice President of Product Development and Engineering, added, "These solutions support board-level to wafer-level packaging, low to high thermal conductivity applications, and small to large die footprints. Leveraging its comprehensive product portfolio, global R&D resources, and localized technical support, Henkel empowers customers to improve thermal performance, package reliability, and mass-production readiness in advanced package designs, while providing vital material support for the next generation of AI development."

Global footprint and multi-site support deliver supply chain resilience

Amid geopolitical shifts and global expansion, semiconductor supply chain resilience has become a priority in international procurement decisions. Henkel has established a robust multi-site support network and operates manufacturing facilities across North America, Europe, and Asia, with established production and technical support hubs across Greater China, South Korea, Japan and Southeast Asia. Flexible backup production sites enable localized, real-time support to meet global customers' capacity expansion and procurement flexibility needs.

Sustainability commitment: advancing circularity in semiconductor materials

Sustainability is a core value at Henkel. In material R&D, the company has pioneered the integration of eco-friendly product design methodologies. For example, Henkel is collaborating with partners to advance circular economy practices, including the use of silver powder from recycled silver, a precious metal widely used in semiconductor packaging. Henkel is committed to working hand in hand with industry partners to reduce carbon emissions and minimize resource waste.

Visit Henkel at SEMICON Taiwan 2026

During SEMICON Taiwan in September, Henkel will present its full suite of material solutions for advanced packaging and high-performance semiconductor applications in Room 404, Hall 1 of the Taipei Nangang Exhibition Center. The company will showcase its technical capabilities across AI infrastructure, HPC, next-generation communications, and Edge AI.

The hospitality suite will feature a variety of interactive experiences, creating opportunities for customers and industry partners to engage directly with Henkel's technical experts. Together, participants will explore innovative solutions for advanced packaging, including thermal management, reliability enhancement, stress mitigation, and readiness for high-volume manufacturing. Through collaboration and knowledge exchange, Henkel continues to support the semiconductor industry's progress toward higher performance, greater reliability, and enhanced resilience.

Details about Henkel consumer electronics materials are available [here](#), and information about its semiconductor solutions can be found [here](#).

LOCTITE® is a registered trademark of Henkel and/or its affiliates in the USA, Germany and elsewhere.

About Henkel

With its brands, innovations and technologies, Henkel holds leading market positions worldwide in the industrial and consumer businesses. The business unit Adhesive Technologies is the global leader in the market for adhesives, sealants and coatings. With Consumer Brands, the company holds leading positions especially in laundry & home care and hair in many markets and categories around the world. The company's three strongest brands are Loctite, Persil and Schwarzkopf. In fiscal 2025, Henkel reported sales of about 20.5 billion euros and adjusted operating profit of around 3.0 billion euros. Henkel's preferred shares are listed in the German stock index DAX. Sustainability has a long tradition at Henkel, and the company has a clear sustainability strategy with specific targets. Henkel was founded in 1876 and today employs a diverse team of about 50,000 people worldwide – united by a strong corporate culture, shared values and a common purpose: "Pioneers at heart for the good of generations." More information at www.henkel.com

Photo material is available at www.henkel.com/press

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Henkel will present its newly launched Loctite ABLESTIK CDF900 series conductive die attach film at SEMICON Taiwan 2026.